

AMENDMENTS TO THE SPECIFICATION

Paragraph on page 21, line 7 from the bottom to page 22, line 1:

The Cu conductive paste having the above composition was applied such that the thickness of the paste on the end surfaces 2a and 2b was 25 μm after drying and the length $[[e]]$ \underline{E} of electrode-covered portions in Fig. 1 was 50 μm . Subsequently, the paste was baked in an oxygen atmosphere at an oxygen concentration of 0 to 5 ppm by keeping a maximum temperature of 850°C for ten minutes to form the first sintered electrode layers 7a and 8a.